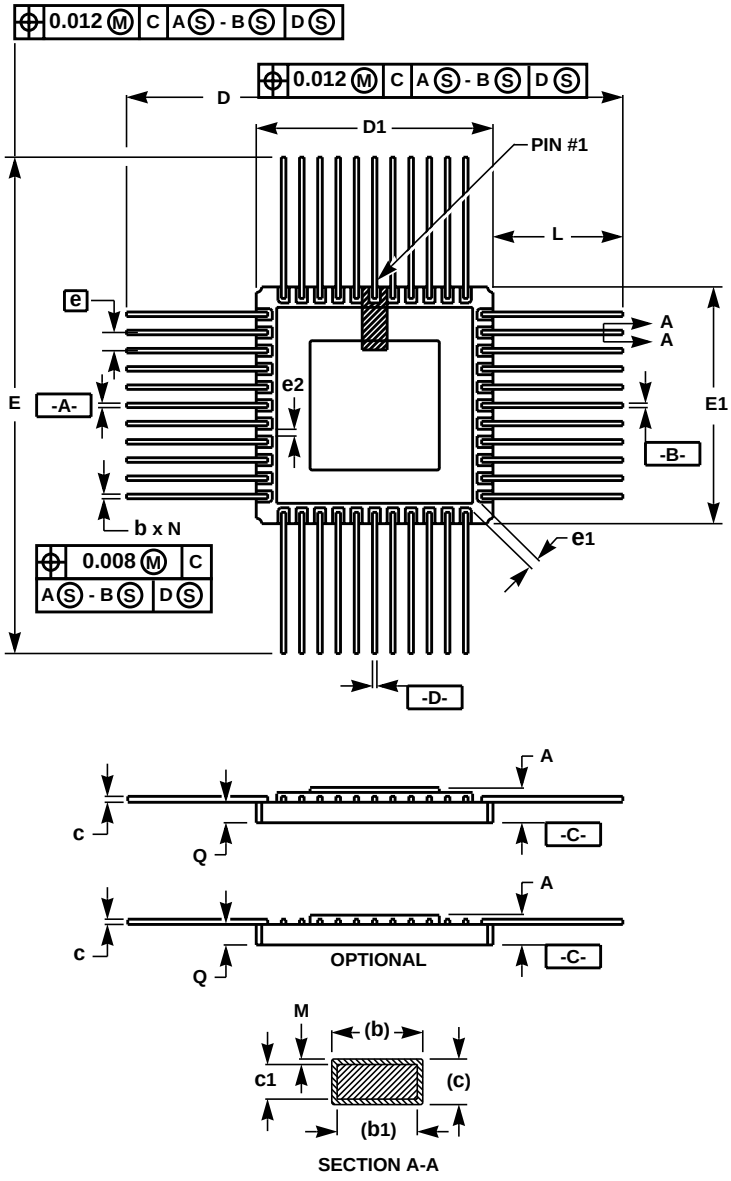
Ceramic Quad Flatpack (CQFP)



R84.A

84 LEAD CERAMIC QUAD FLATPACK PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.105	-	2.67	-
b	0.015	0.022	0.38	0.56	2
b1	0.015	0.019	0.38	0.48	2
c	0.008	0.015	0.20	0.38	2
c1	0.008	0.012	0.20	0.30	2
D	1.800	2.000	45.72	50.80	-
E	1.800	2.000	45.72	50.80	-
D1	1.135	1.170	28.83	29.72	-
E1	1.135	1.170	28.83	29.72	-
e	0.050 BSC		1.27 BSC		-
e1	0.012	-	0.30	-	4
e2	0.012	-	0.30	-	-
L	0.320	0.450	8.13	11.43	-
Q	0.070	0.090	1.78	2.29	6
M	-	0.0015	-	0.04	2
N	84		84		3

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NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
2. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. N is the maximum number of terminal positions.
4. Measure dimension e1 at all four corners.
5. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
6. Dimension Q shall be measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension Q minimum shall be reduced by 0.0015 inch (0.038mm) maximum-when solder dip lead finish is applied.
7. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
8. Controlling dimension: Inch.